低温硬化性ベンゾオキサジンモノマー

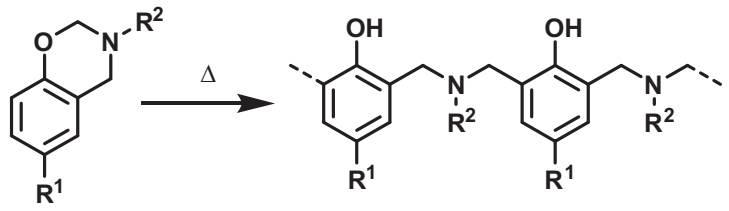
開発品

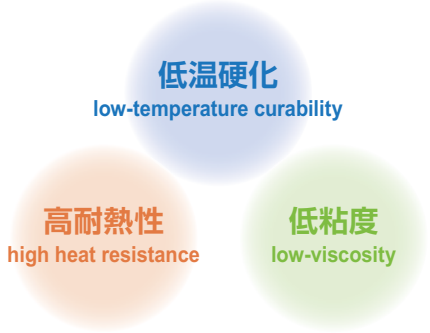
Benzoxazine Monomers with Low Temperature Curable.

低温硬化性、高耐熱性、低粘度なベンゾオキサジンモノマーをご提案致します。

We propose Benzoxazine(BOZ) monomers with low-temperature curability, high heat resistance, low-viscosity.

概要 Outline





●**低温硬化性、耐熱性、低粘度などの特性をバランスよく兼ね備えております。**

Our BOZ monomers have low-temperature curability, high heat resistance and low viscosity.

●**ビスマレイミド（BMI）やエポキシとの配合により、高耐熱性樹脂が得られます。（図1参照）**

By blending our BOZ with BMI or epoxy, it is also possible to enhance the resin Tg more.

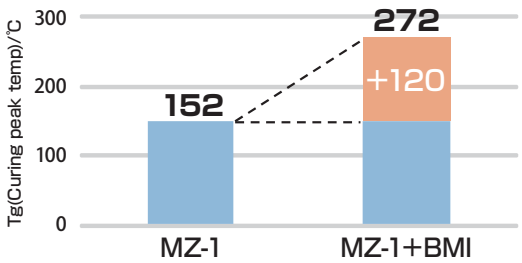


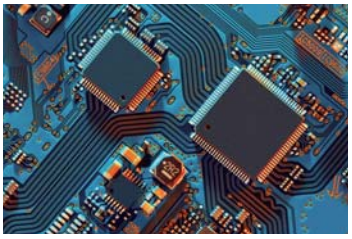
図1. BMIとの配合による相乗効果（MZ-1での実績例）

The high heat resistance of MZ-1 by mixing BMI

各種 BOZ の特性 Characteristics of various BOZ

製品名 Product name	一般的なBOZ conventional BOZ	LA-1 高耐熱グレード high heat resistance	MZ-1 低温硬化グレード low-temperature curing	MZ-3 特殊グレード Special	AZ-2 特殊硬化グレード Special curing
硬化発熱温度 Curing peak temp.	230	227	187	210	209
Tg/℃ Glass transition temp.	222	243	152	205	165
粘度/Pa・S Viscosity	11.9	1.9	3.3	低誘電＋接着性期待 Expect low dielectric constant + high adhesiveness	熱＋ラジカル硬化 Thermosetting + radical polymerization

用途例 Possible applications



半導体封止材
MOLDING COMPOUNDS

接着剤
ADHESIVES